

2018 Applied Materials Technical Symposium: Metrology and Defect Inspection in the Age of IoT

Time		Title	Presenter
13:00	13:10	Opening & Welcome	
13:10	13:50	IPC's Role in Process Development in Santa Clara	Jorge Fernandez, Applied Materials
13:50	14:30	Stochastic Characterization of EUV and DSA using Advanced CDSEM Metrology	Shimon Levi, Applied Materials
14:30	15:10	Recent Technologies for Enhancing Defect Analysis on Un-patterned Wafers	Dror Shemesh, Applied Materials
15:10	15:30	Break	
15:30	16:20	The Secrets of Flash Memory	Chikaaki Kodama, TOSHIBA Memory Corporation
16:20	17:10	Recent Progress in EUV Lithography Materials and Processes to Resolve Stochastic Issues	Toru Fujimori, Fujifilm Corporation
17:10	17:20	Closing	
17:20	19:00	Poster Session & Reception	